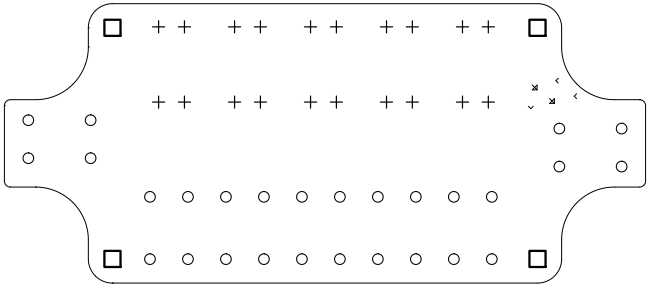


NOTES

- 1.Layers: 2
2.Thickness: 1.6
3.Surface finish: HASL (No Lead)
4.Outer Copper Weight: 2oz
5.Via covering: Tented
6.Min hole size: .3mm
7.Gold Fingers: No
8.Castellated Holes: No
9.Edge Plating: No



Drill Map:

- × 0.635mm / 0.0250" (5 holes)
○ 1.397mm / 0.0550" (28 holes)
+ 1.600mm / 0.0630" (20 holes)
□ 3.000mm / 0.1181" (4 holes) (not plated)

BOARD CHARACTERISTICS

| | | | |
|---------------------------|-------------------------|--------------------|-----------|
| Copper Layer Count: | 2 | Board Thickness: | 1.6722 mm |
| Board overall dimensions: | 84.4000 mm x 36.7750 mm | | |
| Min track/spacing: | 0.0000 mm / 0.0000 mm | Min hole diameter: | 0.3000 mm |
| Copper Finish: | None | Impedance Control: | No |
| Castellated pads: | No | Plated Board Edge: | No |
| Edge card connectors: | No | | |

| Layer Name | Type | Material | Thickness (mils) | Color | Epsilon R | Loss Tangent |
|--------------|---------------------|---------------|------------------|---------------|-----------|--------------|
| F.Silkscreen | Top Silk Screen | Not specified | 0 mils | Not specified | 1 | 0 |
| F.Paste | Top Solder Paste | | 0 mils | | 1 | 0 |
| F.Mask | Top Solder Mask | Not specified | 0.3937 mils | Blue | 3.3 | 0 |
| F.Cu | copper | | 2.8 mils | | 1 | 0 |
| Dielectric 1 | core | FR4 | 59.44882 mils | Not specified | 4.5 | 0.02 |
| B.Cu | copper | | 2.8 mils | | 1 | 0 |
| B.Mask | Bottom Solder Mask | Not specified | 0.3937 mils | Blue | 3.3 | 0 |
| B.Paste | Bottom Solder Paste | | 0 mils | | 1 | 0 |
| B.Silkscreen | Bottom Silk Screen | Not specified | 0 mils | Not specified | 1 | 0 |



1868 SPACE COOKIES

| | | |
|---|------------------|--------|
| Sheet: File: mini-pdb.kicad_pcb | | |
| Title: Mini Power Distribution Board (WCP-1823) | | |
| Size: B | Date: 2025-09-20 | Rev: 2 |
| KiCad E.D.A. 9.0.4 | Id: 1/1 | |